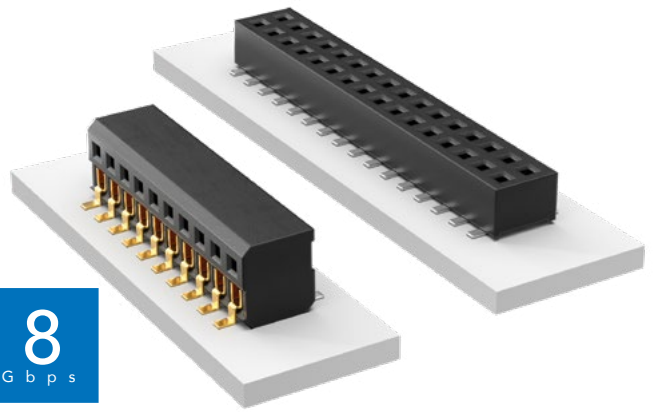


LOW PROFILE DUAL WIPE SOCKET



(1.27 mm) .050" PITCH • CLP SERIES

CLP

Mates:
FTSH, FTS, FW



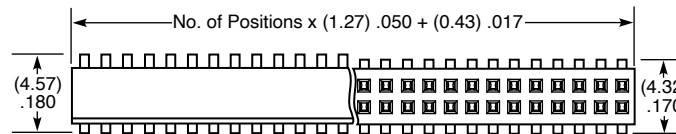
02 thru 50

SPECIFICATIONS

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Sn or Au over
50 μ" (1.27 μm) Ni
Current Rating (CLP/FTSH):
3.4 A per pin
(2 pins powered)
Voltage Rating:
280 VAC/395 VDC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
Top Entry =
(1.40 mm) .055" minimum
Bottom Entry =
(2.41 mm) .095" minimum
plus board thickness
DH Entry =
(2.31 mm) .091" to (2.67 mm) .105"
Max Cycles:
100 with 10 μ" (0.25 μm) Au

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-35)
(0.15 mm) .006" max (36-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)



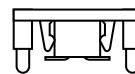
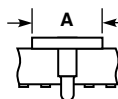
ALSO AVAILABLE

MOQ Required

Single row
Other platings



PIN/ROW	A
04-15	(3.56) .140
16-50	(7.11) .280



-PA OPTION



-P OPTION

Notes:



Severe Environment
Testing qualified; aligns
with MIL-DTL-55302.
Visit samtec.com/set

If odd pins/row, alignment pins are on
middle position on centerline of the part.
If even pins/row, then alignment pins are
between middle two positions.

Some lengths, styles and
options are non-standard,
non-returnable.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View CLP-110-02-F-DH on WIN SOURCE](#)
-  [Samtec Inc. Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management